

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-30V	8mΩ@-10V	-10A
	11mΩ@-4.5V	

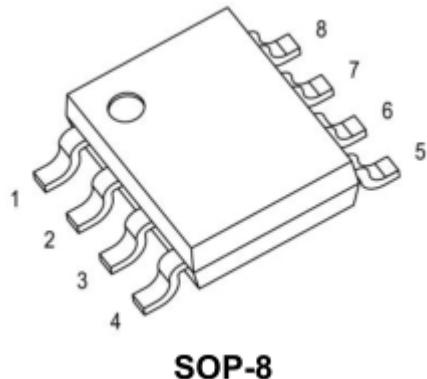
Feature

- TrenchFET Power MOSFET
- Excellent RDS(on) and Low Gate Charge

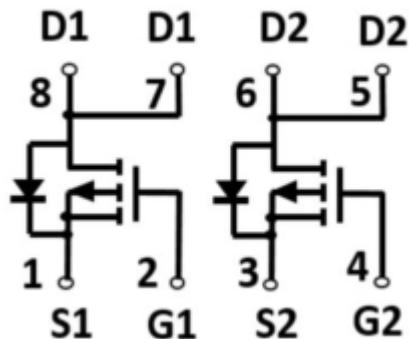
Application

- High power and current handing capability
- Ideal for Lion battery pack applications
- Networking DC-DC Power System
- Load Switch

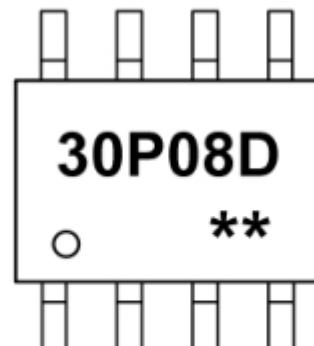
Package



Circuit diagram



Marking



30P08D =Device Code
****** =Week Code

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-10	A
Pulsed Drain Current ¹⁾	I_{DM}	-40	A
Power Dissipation	P_D	1.5	W
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	85	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

Electrical characteristics

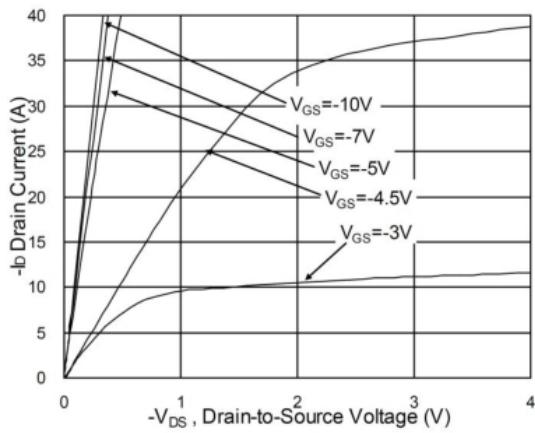
($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$			-1	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	μA
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.8	-2.5	V
Drain-Source On-Resistance	$R_{DS(\text{on})}$	$V_{GS} = -10\text{V}, I_D = -15\text{A}$		8	10	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -10\text{A}$		11	16	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		3448		pF
Output Capacitance	C_{oss}			508		
Reverse Transfer Capacitance	C_{rss}			421		
Switching Characteristics						
Turn-on Delay Time	$T_{d(on)}$	$V_{GS} = -10\text{V}, V_{DD} = -15\text{V}, R_{GEN} = 3.3\Omega, I_D = -1\text{A}$		9.4		nS
Turn-on Rise Time	T_r			10.2		
Turn-off Delay Time	$T_{d(off)}$			117		
Turn-off Fall Time	T_f			24		
Total Gate Charge	Q_g	$V_{DS} = -15\text{V}, V_{GS} = -4.5\text{V}, I_D = -12\text{A}$		30		nC
Gate-Source Charge	Q_{gs}			10		
Gate-Drain Charge	Q_{gd}			10.4		
Drain-Source Diode Characteristics						
Body Diode Voltage	V_{SD}	$V_{GS} = 0\text{V}, I_s = -1\text{A}$			-1.2	V

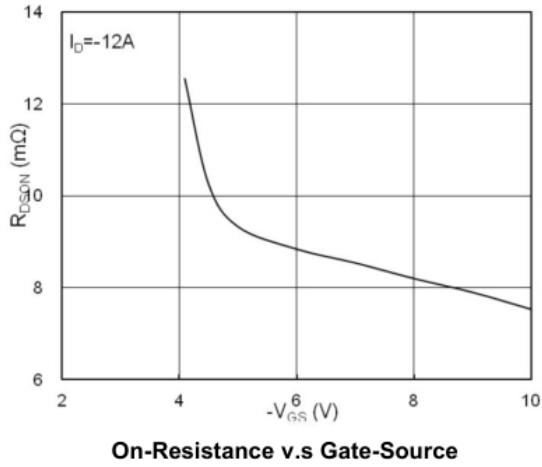
Note:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, $t \leq 10\text{s}$.
3. Pulse Test: Pulse Width $\leq 80\mu\text{s}$, Duty Cycle $\leq 0.5\%$.
4. Guaranteed by design, not subject to producing.

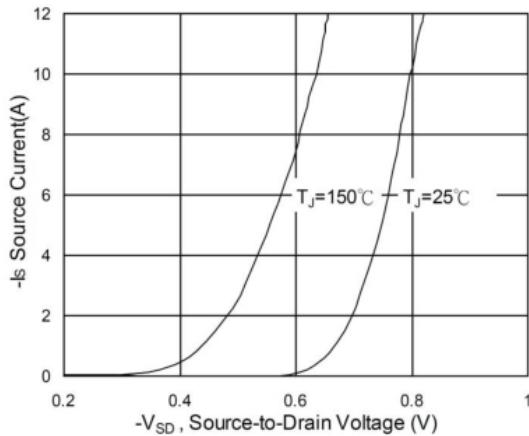
Typical Characteristics



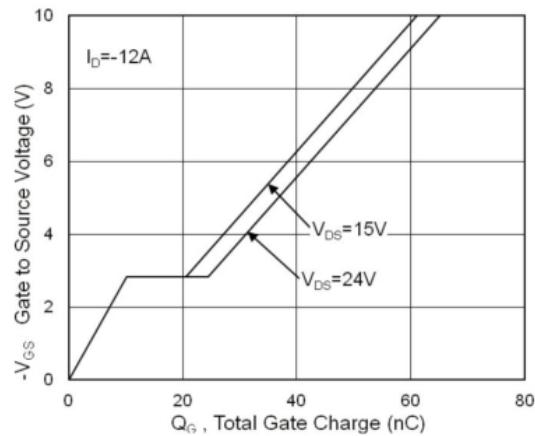
Typical Output Characteristics



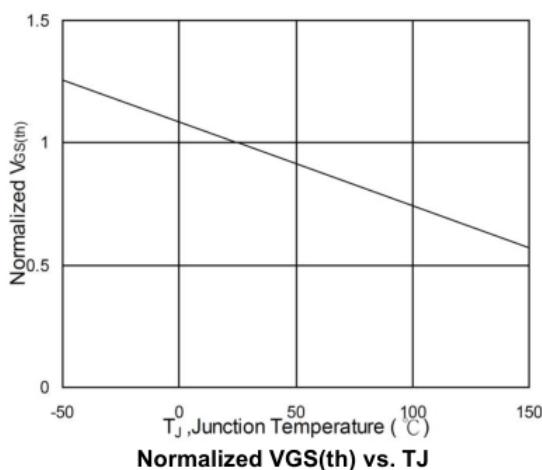
On-Resistance v.s Gate-Source



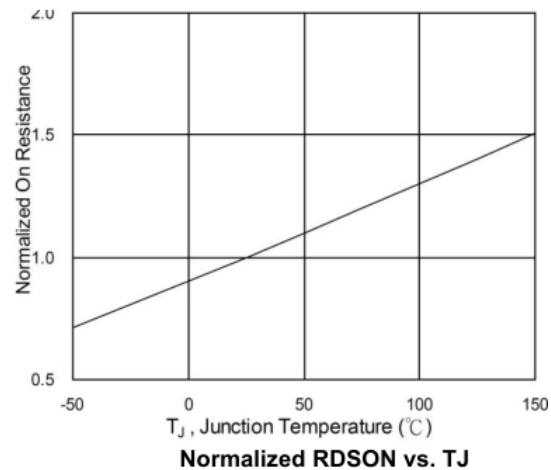
Forward Characteristics Of Reverse



Gate-Charge Characteristics



Normalized VGS(th) vs. TJ

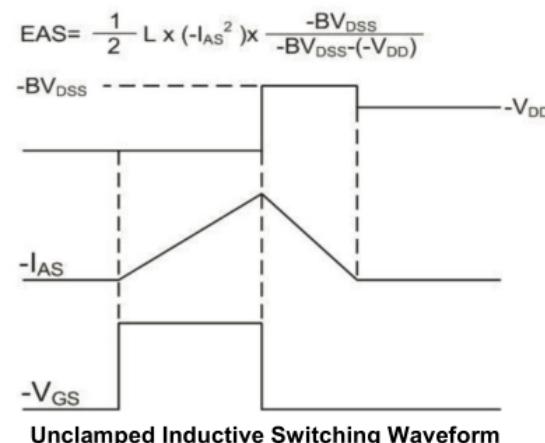
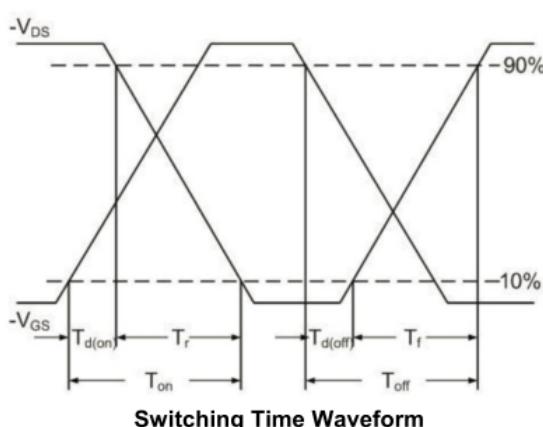
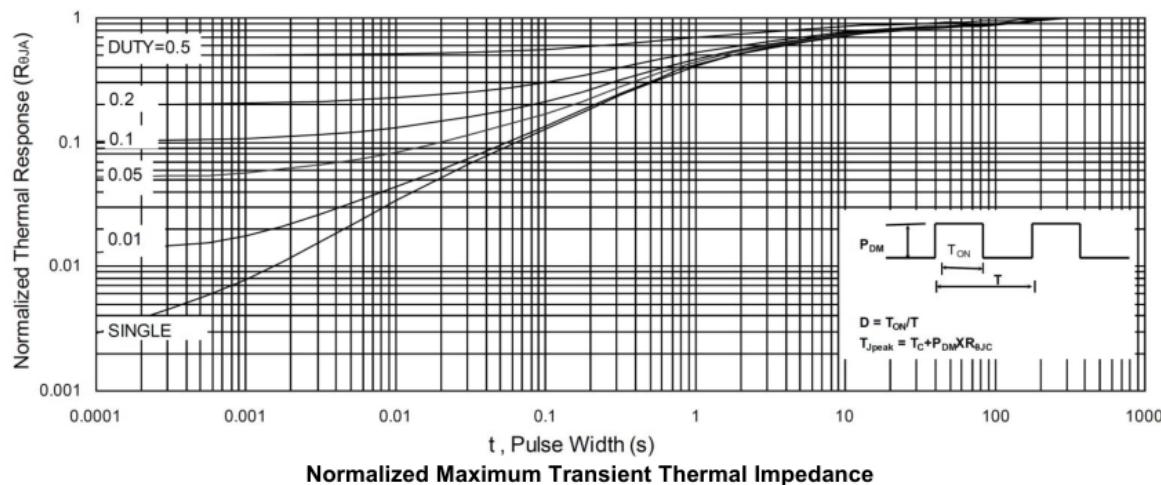
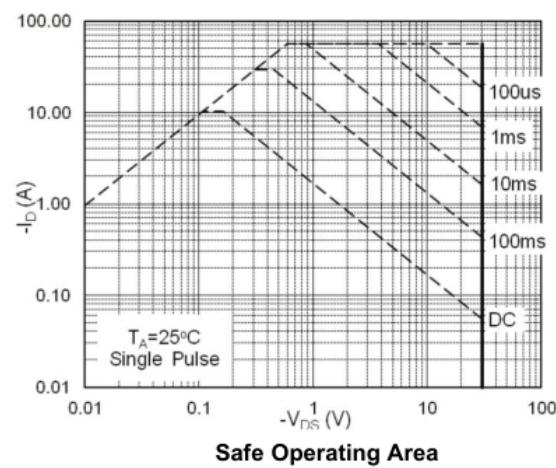
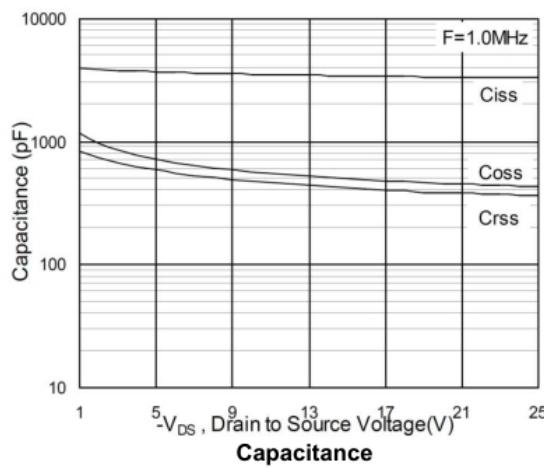


Normalized RDSON vs. TJ

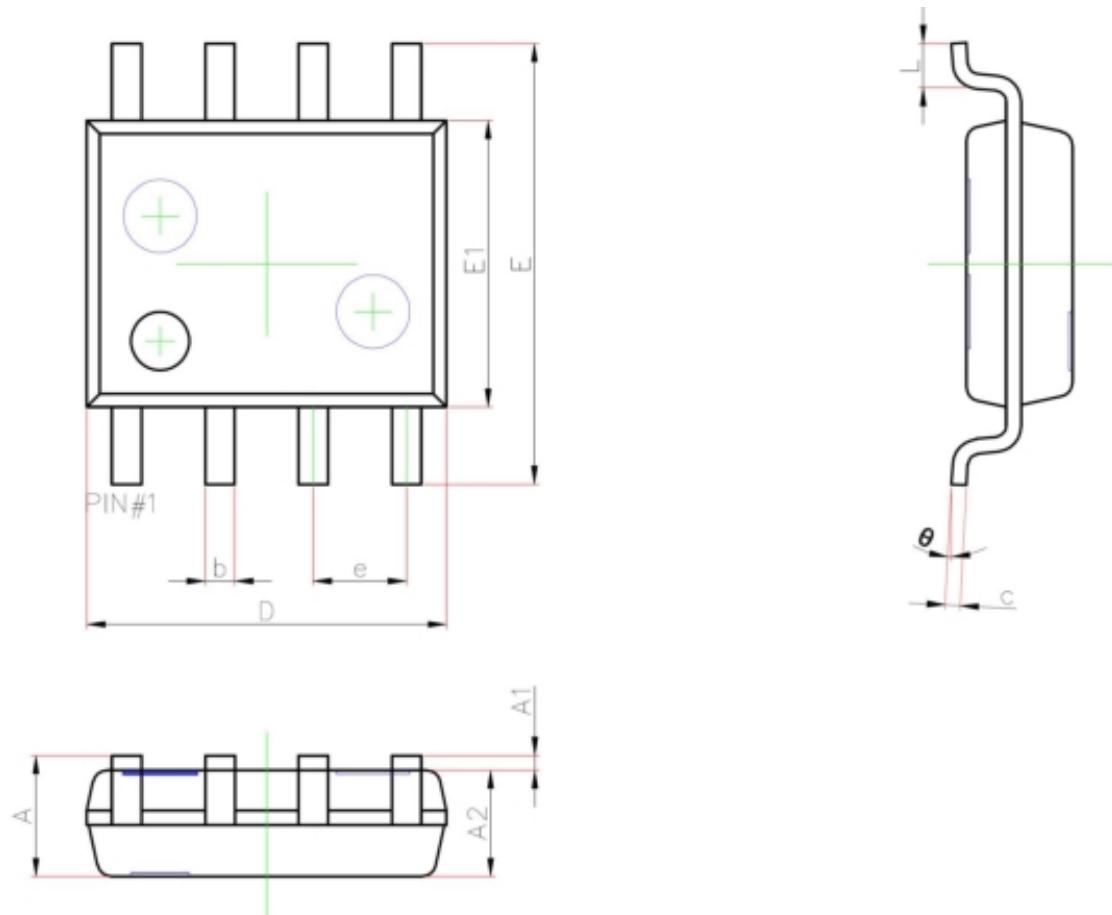


ZL MOSFET

ZL30P08D



SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°